

PCB Cleaner – concentrated

SYS-CLEAN[®] BC3.0 is a water-based cleaning medium for flux removal of printed circuit boards, ceramic substrates, lead frames and power modules

SYS-CLEAN[®] BC3.0 is well suited to prepare surfaces for subsequent wire bonding and coating processes. The cleaning agent is suitable for spray-in-air and spray-under-immersion.



Application

Pollution	Suitability
Low solid flux	✓ ✓
Colophonium flux	✓ ✓
Water soluble flux	✓ ✓
Solder paste leaded / unleaded	✓ ✓
SMT adhesives	✗

Application Parameters

Parameter	
Application temperature	50 - 60°C
Cleaning time approx.	10 - 30 min.
Rinsing	DI-Water
Drying	convection/ compressed air
Application concentration	15 – 30% in DI-Water

✓ ✓ = Excellent ✓ = Optimal ○ = Optional ✗ = Not recommended

Specifications

SYS-CLEAN[®] BC3.0 is supplied as concentrate

pH-Value	10,5 – 11,5
Density (at 20°C)	0,9634 g/cm ³
Refractive index (at 20°C)	1,4266
Flashpoint	>100°C
Initial boiling point and boiling range	No information

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Application	
Spray-in-air	✓ ✓
Immersion cleaning air agitated	✓ ✓
Spray under Immersion	✓ ✓
Ultrasonic	✗
Manual cleaning	✓

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Advantages:

SYS-CLEAN[®] BC3.0 is configured extremely gently and has a good cleaning performance

The high loading capacity with the best filterability ensures a particularly cost-effective process

The cleaner can be used in the spray process as well as in immersion systems.

Availability:

SYS-CLEAN[®] BC3.0 concentrate is available in the following sizes

Item number: 64905781 – 25L



Registration, Evaluation and
Authorisation of Chemicals

The product is free of
questionable ingredients
according to the SIN- &
SVHC-Lists



100% compliant with EU
guidelines RoHS 1 & 2,
WEEE